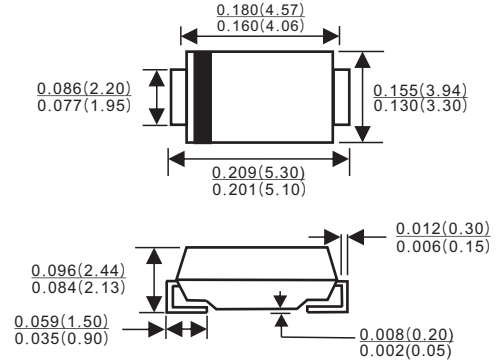




Features

- ✦ Glass passivated junction chip
- ✦ For surface mounted applications
- ✦ Low profile package
- ✦ Built-in strain relief
- ✦ Ideal for automated placement
- ✦ Easy pick and place
- ✦ Super fast recovery time for high efficiency
- ✦ Glass passivated chip junction
- ✦ High temperature soldering:
260°C/10 seconds at terminals
- ✦ Plastic material used carries Underwriters
Laboratory Classification 94V-0

SMB/DO-214AA



Dimensions in inches and (millimeters)

Mechanical Data

- ✦ Cases: Molded plastic
- ✦ Terminals: Pure tin plated, lead free.
- ✦ Polarity: Indicated by cathode band
- ✦ Weight: 0.21 gram

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.
Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%

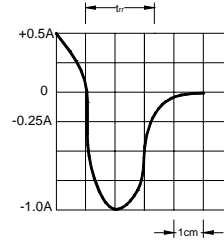
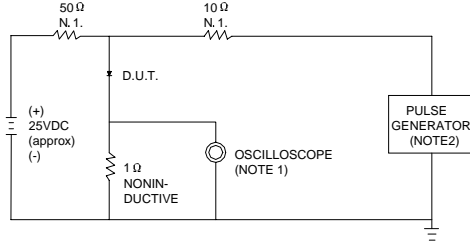
Parameter	Symbol	ES 3AB	ES 3BB	ES 3CB	ES 3DB	ES 3EB	ES 3GB	ES 3HB	ES 3JB	Units
Marking code		ES3A	ES3B	ES3C	ES3D	ES3E	ES3G	ES3H	ES3J	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	500	600	V
Maximum RMS Voltage	V_{RMS}	35	70	105	140	210	280	350	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	500	600	V
Maximum Average Forward Rectified Current See Fig. 1	$I_{(AV)}$	3.0								A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) @ $T_L = 100^\circ\text{C}$	I_{FSM}	100								A
Maximum Instantaneous Forward Voltage @ 3.0A	V_F	0.95			1.25		1.7			V
Maximum DC Reverse Current @ $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$	I_R	10				500				uA
Maximum Reverse Recovery Time (Note 1)	T_{rr}	35								nS
Typical Junction Capacitance (Note 2)	C_j	45				30				pF
Typical Thermal Resistance (Note 3)	$R_{\theta JA}$ $R_{\theta JL}$	47				12				$^\circ\text{C} / \text{W}$
Operating Temperature Range	T_J	-55 to +150								$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150								$^\circ\text{C}$

- Notes:
- Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $IRR=0.25\text{A}$
 - Measured at 1 MHz and Applied $V_R=4.0$ Volts
 - Units Mounted on P.C.B. with 0.6" x 0.6" (16mm x 16mm) Copper Pad Areas



Ratings AND Characteristic Curves

FIG.1 -- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES:1.RISE TIME = 7ns MAX.INPUT IMPEDANCE = 1MΩ .22pF.
2.RISE TIME =10ns MAX.SOURCE IMPEDANCE=50 Ω .

SET TIME BASE FOR 20/30 ns/cm

FIG.2 -- TYPICAL FORWARD CHARACTERISTIC

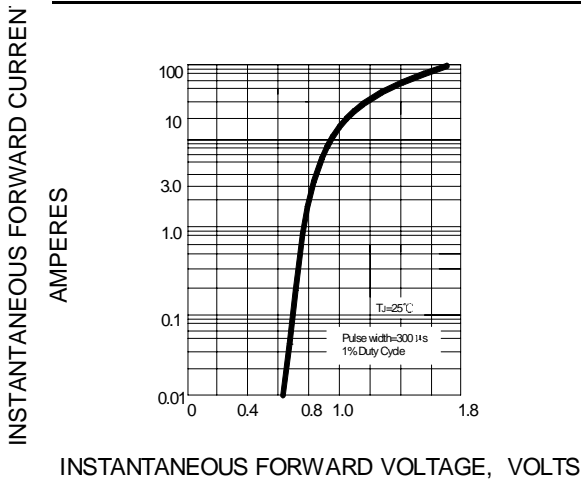


FIG.3 -- FORWARD DERATING CURVE

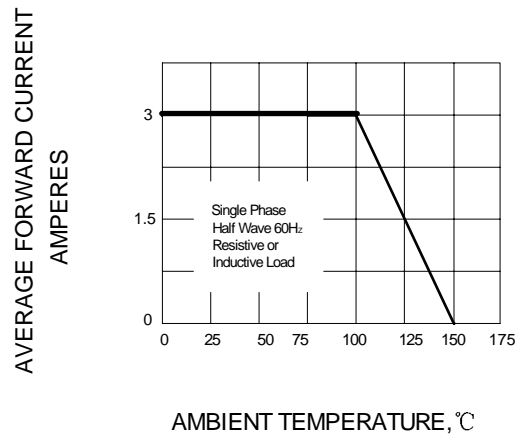


FIG.4 -- TYPICAL JUNCTION CAPACITANCE

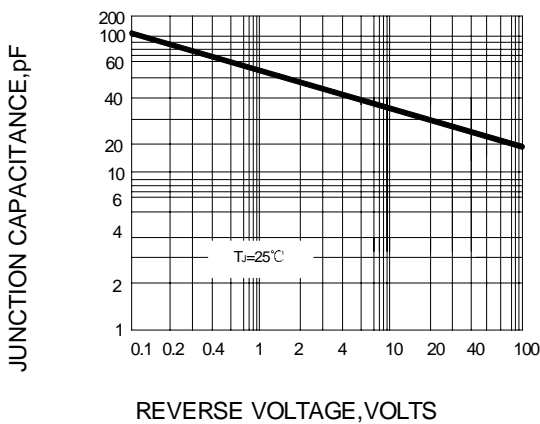
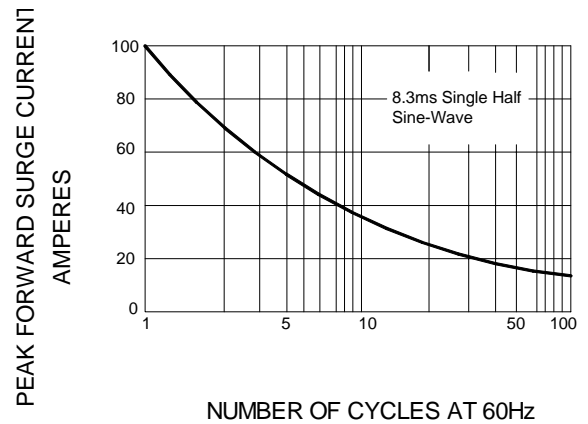


FIG.5 -- PEAK FORWARD SURGE CURRENT



PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMB	3000/REEL	48000	36X35.8X36.5	12.00	11.00